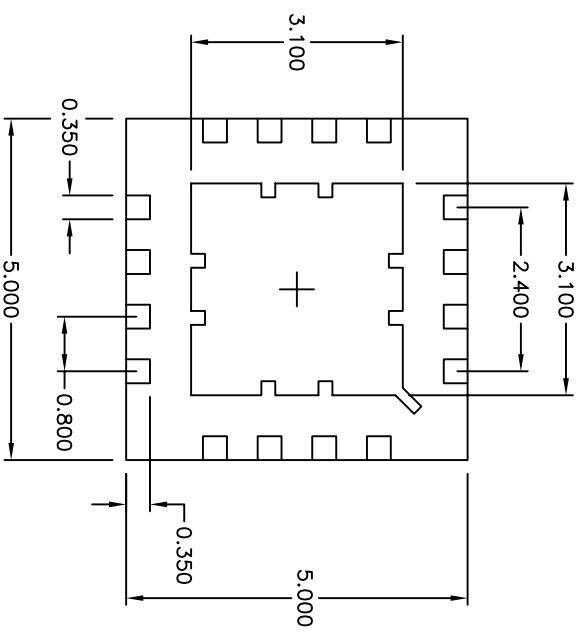
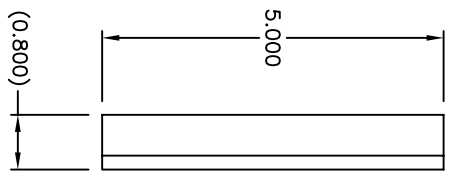
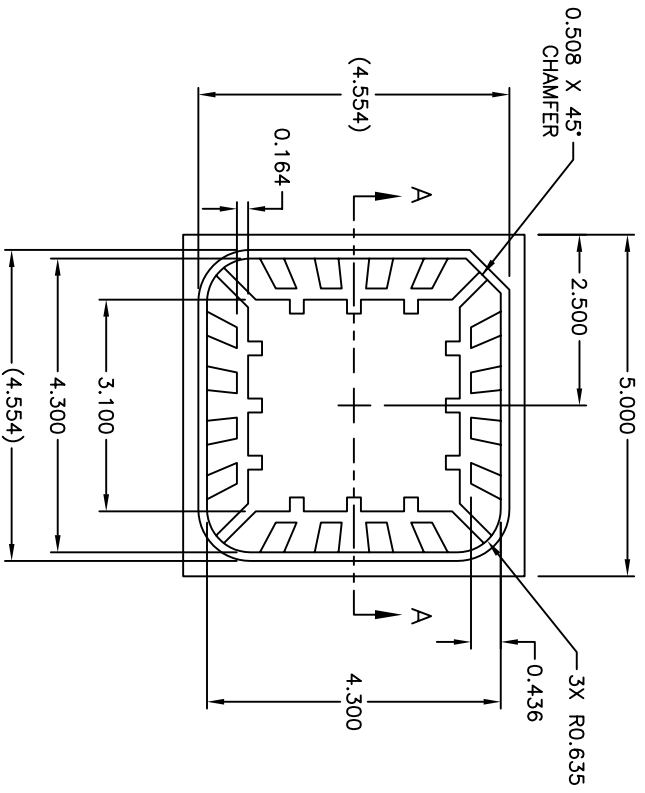


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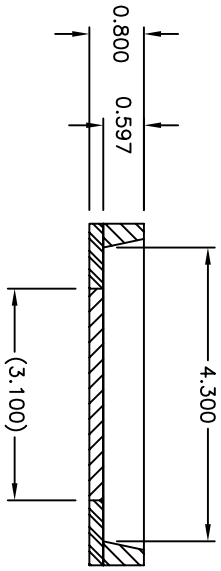
1

REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	D.BEVANDO
10490	10/27/05	PRODUCTION RELEASE	



TOP VIEW

BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  2. LEAD FINISH: COPPER, FH 194.
  3. LEAD FINISH: FULL GOLD PLATE.
  4. LEAD THICKNESS: 0.2030 ±.0076.
  5. DIE PAD: 3.100 X 3.100.
  6. JEDEC OUTLINE: MO-220 (VHHB).



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XXX ± 0.15 X.XXXX ± ---

DO NOT SCALE DRAWING

DRAWN BY W. GRIFFITTS  
DATE 07/05/05

APP BY P. FLASKERUD  
DATE 07/05/05

CUSTOMER: ---

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16 Lead 5.00mm x 5.00mm  
MLP Open-Pak

SIZE	PART NO.	REV
A	MLP5X5-16-OP-01	1

SCALE NONE CAD FILE MLP5X5-16-OP-01-RI.DWG SHEET 1 OF 1

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